



In re Applicant:

Matthew Prince et al.

Serial No.: 10/762,849

Filed: January 22, 2204

Reducing Wafer Defects from For:

Chemical Mechanical Polishing

9999999999

Assignee:

Docket:

Art Unit:

Examiner:

Intel Corporation

Hadi Shakeri

ITL.0941US

P15694

3723

Mail Stop Amendment Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

REPLY TO PAPER NO. 081105

Sir:

In response to the office action mailed August 15, 2005, please amend the abovereferenced patent application as follows:

Date of Deposit: November 10, 2005

I hereby certify under 37 CFR 1.8(a) that this correspondence is being deposited with the United States Postal Service as **first class mail** with sufficient postage on the date indicated above and is addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, J.A. 22313-1450.